

Attorney Docket No.: CPAC 1001-1 US  
USSN 09/802,443



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Linda Shaw  
Linda Shaw

May 10, 2002  
Date

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TECHNOLOGY CENTER 2800

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of )  
Rajendra D. Pendse *et al.* )  
 ) Examiner: Unknown  
Application No.: 09/802,443 )  
 ) Group Art Unit: 2811  
Filed: March 9, 2001 )  
 ) Date: May 10, 2002  
Title: **Flip chip-in-leadframe** )  
 **package and process** )  
 )

**SEPARATE LETTER TO OFFICIAL DRAFTSPERSON**

Official Draftsperson  
Commissioner Of Patents  
Washington, D.C. 20231

Official Draftsperson:

In connection with the above-referenced U. S. patent application, transmitted herewith are the following papers:

[X] Two (2) sheets of formal drawing(s) (Figs 1, 2, 3, 4, 5, and 6).

Authorization is hereby given to deduct from or credit to Deposit Account No. 50-0869 (CPAC 1001-1 US), any fees that may be required with this matter. A duplicate of this paper is enclosed.

Respectfully submitted,  
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